



Laird™ Tflex™ UT20500

Tflex™ UT20000 is a specially formulated ultra-thin gap filler thermal interface material designed for thin interfaces that offers excellent thermal performance and high compliancy. It is designed without embedded reinforcing fiberglass to minimize contact resistance, yet still allows easy material handling and durability during assembly. Tflex™ UT20000 provides excellent interfacing and its ability to wet out mating surfaces allows for efficient transfer of heat away from components. It is an ideal choice for low-pressure applications and optimum solution in handheld devices with thin interface gap and limited space requirements. Tflex™ UT20000 is electrically non-conductive, stable from -50°C thru 200°C and offered in thicknesses that range from 0.008" (200 µm) up to 0.040" (1000 µm). A polyimide film option is available for increased electrical resistance and a tear resistant top surface.

TECHNICAL DATA SHEET | (EFFECTIVE 24FEB25)

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PHYSICAL PROPERTY	TEST METHOD	UNIT	VALUE
Construction & Composition		-	Ceramic filled silicone sheet
Color		-	Grey
Thickness Range		µm in	200 -1000 0.008 - 0.04
Thermal Conductivity	Hot Disk	w/mk	3.0
Density	Helium Pycnometer	g/cc	3.2
Outgassing TML	ASTM E595	%	0.34
Outgassing CVCM	ASTM E595	%	0.09
Temperature Range	Laird Test Method	°C	-50 to 200
Hardness (Shore 00)	ASTM 2240	µm	83.3 (200-375) 56.4* (400-1000)
Rth @ 200 µm, 10 psi, 50°C	ASTM D5470	°C-in ² /w	0.25
Dielectric Constant @ 1 MHz	ASTM D150	-	5.87
Volume Resistivity	ASTM D257	Ω-cm	2.2 × 10 ¹⁵
UL Flammability Rating	UL 94	-	V-0